



FMC+ TO FMC REV E2 Bill of Materials

Item #	Designator	Quantity	Value	PartNumber	Manufacturer	Description	PackageReference
1	!PCB1	1		FMC+ TO FMC	Any	Printed Circuit Board	
2	J1	1		ASP-184329-01	Samtec	Socket, 50 mil, 40x14, Gold, SMT	Socket, 50 mil, 40x14, Gold, SMT
3	J2	1		ASP-134488-01	Samtec	Connector, 1.27mm, 40x10, Black, SMT	Connector, 1.27mm, 40x10, SMT
4	J3	1		QSH-030-01-L-D-A	Samtec	Receptacle, 0.5 mm, 30x2, Gold, TH	Receptacle, 0.5 mm, 30x2, TH
5	J4	0		ASP-184330-01	SAMTEC	14 ROW .050 PITCH TERMINAL ARRAY ASM.	
6	LBL1	1		THT-14-423-10	Brady	Thermal Transfer Printable Labels, 0.650" W x 0.200" H - 10,000 per roll	PCB Label 0.650"H x 0.200"W
7	R20, R21, R22, R23, R24, R26	6	0	ERJ-1GN0R00C	Panasonic	RES, 0, 5%, 0.05 W, AEC-Q200 Grade 0, 0201	0201
8	R7, R19	2	0	CRCW04020000Z0ED	Vishay-Dale	RES, 0, 5%, 0.063 W, 0402	0402
9	R1, R2, R3, R4, R5, R6	0	0	ERJ-1GN0R00C	Panasonic	RES, 0, 5%, 0.05 W, AEC-Q200 Grade 0, 0201	0201
10	R8, R25, R27	0	0	CRCW04020000Z0ED	Vishay-Dale	RES, 0, 5%, 0.063 W, 0402	0402
11	FID1, FID2, FID3	0		N/A	N/A	Fiducial mark. There is nothing to buy or mount.	Fiducial

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